

Amendments to the Claims:

This listing of the claims will replace all prior versions of the claims in the application:

1. (Currently amended) A thermal head, comprising:

a substrate;

a thermal storage layer disposed on one main surface of the substrate so as to extend to an edge of the substrate, the thermal storage layer being formed of glass;

electrodes disposed on or above the thermal storage layer apart from the edge of the substrate;

heat-generating resistors disposed above the thermal storage layer apart from the edge of the substrate, the heat-generating resistors being connected to the electrodes; and

a first covering layer disposed on or above the electrodes and the heat-generating resistors so as to extend from atop the electrodes and the heat-generating resistors toward atop the thermal storage layer on the edge of the substrate; and

~~the first covering layer extending from atop the electrodes and the heat-generating resistors toward atop the thermal storage layer on the edge of the substrate, a protection film being disposed on or above the first covering layer disposed on or above the electrodes and the heat-generating resistors, and~~

an edge of the protection film being not disposed above the edge of the substrate, and being positioned between the electrodes and the heat-generating resistors, and the edge of the substrate.

2. (Cancelled)

3. (Currently Amended) The thermal head according to claim 1,
wherein the first ~~covering~~coverage layer has a higher Vickers hardness than that of the thermal storage layer.

4. (Previously Presented) The thermal head according to claim 1,
wherein the protection film has a lower Vickers hardness than that of the thermal storage layer.

5. (Previously Presented) The thermal head according to claim 1, comprising:
a second covering layer disposed between the first covering layer and the protection film.

6. (Previously Presented) The thermal head according to claim 1,
wherein the first covering layer is made of SiN.

7. (Previously Presented) The thermal head according to claim 5,
wherein the second covering layer is made of SiON.

8. (Currently Amended) The thermal head according to claim 5,
wherein the second covering layer is made of ~~SiO₂~~ SiO₂.

9. (Previously Presented) The thermal head according to claim 1, comprising:
a resin layer disposed above a region extending from the edge of the substrate
to the protection film,
a portion of the resin layer positioned above the edge of the substrate being
disposed higher than a portion of the resin layer positioned above the protection
film.

10. (Previously Presented) A thermal printer, comprising:
the thermal head according to claim 1;
a conveyance mechanism that conveys a recording medium on a plurality of
heat-generating portions; and
a platen roller that presses the recording medium on the plurality of heat-
generating portions.

11. (New) A thermal head, comprising:
- a substrate;
 - a thermal storage layer disposed on one main surface of the substrate so as to extend to an edge of the substrate, the thermal storage layer being formed of glass;
 - electrodes disposed on or above the thermal storage layer apart from the edge of the substrate;
 - heat-generating resistors disposed above the thermal storage layer apart from the edge of the substrate, the heat-generating resistors being connected to the electrodes; and
 - a first covering layer disposed on or above the electrodes and the heat-generating resistors so as to extend from atop the electrodes and the heat-generating resistors toward atop the thermal storage layer on the edge of the substrate;
 - a protection film disposed on or above the first covering layer disposed on or above the electrodes and the heat-generating resistors, an edge of the protection film being not disposed above the edge of the substrate; and
 - a second covering layer disposed between the first covering layer and the protection film.
12. (New) The thermal head according to claim 11,
wherein the first covering layer is made of SiN.

13. (New) The thermal head according to claim 11,
wherein the second covering layer is made of SiON.

14. (New) The thermal head according to claim 11,
wherein the second covering layer is made of SiO₂.

15. (New) The thermal head according to claim 11, comprising:
a resin layer disposed above a region extending from the edge of the substrate
to the protection film,
a portion of the resin layer positioned above the edge of the substrate being
disposed higher than a portion of the resin layer positioned above the protection
film.

16. (New) A thermal printer, comprising:
the thermal head according to claim 11;
a conveyance mechanism that conveys a recording medium on a plurality of
heat-generating portions; and
a platen roller that presses the recording medium on the plurality of heat-
generating portions.

17. (New) A thermal head, comprising:

a substrate;

a thermal storage layer disposed on one main surface of the substrate so as to extend to an edge of the substrate, the thermal storage layer being formed of glass;

electrodes disposed on or above the thermal storage layer apart from the edge of the substrate;

heat-generating resistors disposed above the thermal storage layer apart from the edge of the substrate, the heat-generating resistors being connected to the electrodes; and

a first covering layer disposed on or above the electrodes and the heat-generating resistors so as to extend from atop the electrodes and the heat-generating resistors toward atop the thermal storage layer on the edge of the substrate;

a protection film disposed on or above the first covering layer disposed on or above the electrodes and the heat-generating resistors, an edge of the protection film being not disposed above the edge of the substrate; and

a resin layer disposed above a region extending from the edge of the substrate to the protection film,

a portion of the resin layer positioned above the edge of the substrate being disposed higher than a portion of the resin layer positioned above the protection film.

18. (New) The thermal head according to claim 17,
wherein the first covering layer has a higher Vickers hardness than that of the thermal storage layer.

19. (New) The thermal head according to claim 17,
wherein the protection film has a lower Vickers hardness than that of the thermal storage layer.

20. (New) The thermal head according to claim 17,
wherein the first covering layer is made of SiN.

21. (New) A thermal printer, comprising:
the thermal head according to claim 17;
a conveyance mechanism that conveys a recording medium on a plurality of heat-generating portions; and
a platen roller that presses the recording medium on the plurality of heat-generating portions.